

PATENT ABSTRACTS OF JAPAN

(11) Publication number:

06-262375

(43) Date of publication of application : 20.09.1994

(51)Int.Cl.

B23K 20/00
H01B 1/22
H05K 1/09
H05K 3/32
H05K 3/40
H05K 3/46

(21) Application number : 05-134404

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(22) Date of filing : 04.06.1993

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(30)Priority

Priority number : 04145276
04239064
05 3127

Priority date : 05.06.1992
08.09.1992
12.01.1993

Priority country : JP

JP

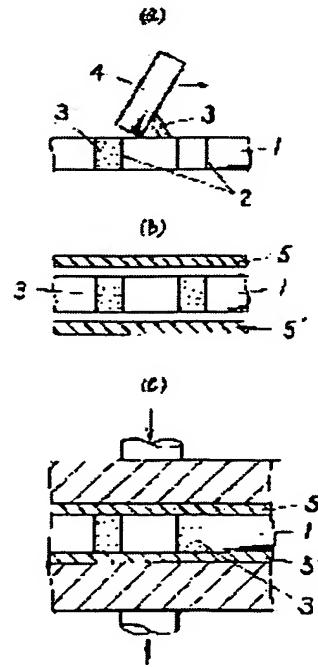
JP

(54) DIFFUSED JUNCTION METHOD FOR COPPER OR COPPER ALLOY AT LOW TEMPERATURE, AND MANUFACTURE OF CONDUCTIVE PASTE AND MANUFACTURE WIRING BOARD USING THE SAME

(57)Abstract:

PURPOSE: To provide the manufacture method for a multilayer wiring board excellent in an electrical characteristic capable of joining copper or copper alloys at a low temperature, further a simple work method is used by applying this theory.

CONSTITUTION: Metals are joined together by heating and pressurizing the metals at 170° C or over, providing a conductive paste layer whose main composing elements are conductive powder consisting of the thin film layer of a noble metal, an oxidized film remover layer or copper, or their alloys and activator on a surface whose at least one side is copper or a copper alloy. Further, by applying this connecting theory, after rubbing conductive paste 3 whose main composing elements are conductive powder consisting of a noble metal, copper or their alloys and activator, into a hole 2 made in the prescribed part of an insulating adhesive material layer 1, the insulating adhesive material layer 1 is placed between copper foils 5 and 5', and a multilayer wiring board is manufactured by heating and pressurizing it at 170° C or over.



LEGAL STATUS

[Date of request for examination] 12.10.1998

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

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